

IN THE CLAIMS:**Please amend the claims as follows:**

1 (currently amended). An ~~optoelectronic~~ apparatus, comprising:

a first package comprising a first window, said first package to house a first device to perform a first optical or optoelectronic function; and

a second package, being a same size and shape as the first package, comprising a second window, said second package to house a second device to perform a second optical or optoelectronic function;

said first package attached to said second package to allow a light beam to pass between said first window and said second window.

2 (currently amended). The ~~optoelectronic~~ apparatus as recited in claim 1, wherein either of said first window and said second window comprise a transparent material to form a hermetic package.

3 (currently amended). The ~~optoelectronic~~ apparatus as recited in claim 1 wherein either of said first window and said second window comprise an opening.

4 (currently amended). The ~~optoelectronic~~ apparatus as recited in claim 1

wherein said second package comprises a third window to couple with a third package.

5 (currently amended). The ~~optoelectronic~~ apparatus, as recited in claim 1 wherein said second package comprises a feedthrough for a fiber.

6 (currently amended). The ~~optoelectronic~~ apparatus as recited in claim 1 wherein either of said first device and said second device comprises a passive device.

7 (currently amended). The ~~optoelectronic~~ apparatus as recited in claim 6 wherein said passive device comprises one of a mirror and a splitter.

8 (currently amended). The ~~electronic~~ apparatus as recited in claim 1 wherein either of said first device and said second device comprises an active device.

9 (currently amended). The ~~electronic~~ apparatus as recited in claim 8 wherein said active device comprises one of a laser, and amplifier, a modulator, and an optical isolator.

10 (currently amended). A method, comprising:

providing a plurality of same size and shape packages each housing a

device for performing an optical or optoelectronic function;
providing at least one window in each of said packages;
coupling said plurality of packages together; and
transmitting a beam between windows of adjacent packages.

11 (original). The method as recited in claim 10, further comprising: one of soldering, welding or epoxying said plurality of packages together.

12 (original). The method as recited in claim 10, further comprising: providing a package comprising a feedthrough for a fiber.

13 (previously amended). The method as recited in claim 10 wherein at least one said device comprises a passive device.

14 (original). The method as recited in claim 13 wherein said passive device comprises one of a mirror and a splitter.

15 (previously amended). The method as recited in claim 10 wherein at least one said device comprises an active device.

16 (original). The method as recited in claim 15 wherein said active device comprises one of a laser, an amplifier, a modulator, and an optical isolator.

17 (currently amended). A modular optoelectronic system, comprising:

a plurality of same size and shape hermetically sealed packages, each comprising at least one window;

a device in each of said plurality of packages to perform a particular function for an optoelectronic product;

coupling means for modularly coupling said packages together to pass a collimated beam between adjacent windows to optically connect each said device to form said optoelectronic system.

18 (original). The modular optoelectronic system as recited in claim 17, further comprising:

a package including a fiber feedthrough.

19 (original). The modular optoelectronic system as recited in claim 17 wherein each said device comprises one of a passive device and an active device.

20 (original). The modular optoelectronic system as recited in claim 17 wherein said coupling means comprises one of solder, weld, and epoxy.